

03-27-2001



101648625

PATENT

Docket No.: NAUP0235USA

3-13-01

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

RECORDING COVER SHEET



- 1. Assignor: Sun-Chieh Chien , Chien-Li Kuo
- 2. Assignee: UNITED MICROELECTRONICS CORP.  
No.3, Li-Hsin Road 2,  
Science-Based Industrial Park,  
Hsin-Chu, Taiwan, R.O.C.

09/803881

- 3. Nature of Conveyance: Assignment of patent
- 4. Reference number: Application filed herewith.
- 5. Correspondence to: Winston Hsu  
5F, No. 389, Fu-Ho Rd.,  
234 YungHo City, Taipei Hsien,  
Taiwan, R.O.C.

40E

- 6. Number of applications affected by this recording: 1  
Total fee: ( 1 x \$ 40 ) = \$ 40.00 Payment by check enclosed  
Authorization is hereby given to charge the over payment to deposit account #500801

- 7. Execution date of the document to be recorded: 03/05/2001

- 8. Total number of pages including cover sheet: 3

- 9. I declare under penalty of perjury that to the best of my knowledge and belief, the information contained on this cover sheet is true and correct, and that any copy submitted herewith is a true and correct copy of the original document.

03/15/2001 MLAKW1 00000016 09803881

02 FC:581

40.00 DP

Date: 3/9/2001

Winston Hsu

Winston Hsu  
U.S. Patent Agent  
Reg. No.:41,526

**ASSIGNMENT OF INVENTION**

In consideration of the payment by ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration.

**ASSIGNORS (Inventors):**

Name: Sun-Chieh Chien Nationality: R.O.C.

Address: No.7, Lane 30, Tun-Feng Rd., Hsiang-Shan, Hsin-Chu City, Taiwan, R.O.C.

Name: Chien-Li Kuo Nationality: R.O.C.

Address: No.22, Alley 102, Lane 648, Ming-Hu Rd., Hsin-Chu City, Taiwan, R.O.C.

Hereby sells, assigns and transfers to **UNITED MICROELECTRONICS CORP.**  
(hereinafter 'Assignee'), of (Assignee address)

**No.3, Li-Hsin Road 2, Science-Based Industrial Park, Hsin-Chu, Taiwan, R.O.C.**

, and the successors assigns and legal representatives of the ASSIGNEE the entire right, title, and interest in and to any and all improvements which are disclosed in the invention entitled:

**"Method for in-situ fabrication of a landing via and a strip contact in an embedded memory"**

Which is found in :

- (a) \_\_\_\_\_ U.S. patent application executed on even date
- (b) \_\_\_\_\_ U.S. patent application executed on \_\_\_\_\_
- (c) \_\_\_\_\_ U.S. application serial no. \_\_\_\_\_
- (d) \_\_\_\_\_ patent no. \_\_\_\_\_ issued \_\_\_\_\_

and, in and to, all Letters Patent to be obtained for said invention by the above application or ant continuation, division, renewal, or substitute thereof, and as to letters patent any reissue or re-examination thereof